



Material Content Data Sheet



Sales Product Name		SAK-C167CS-LM CA+		Issued		25. September 2017		
MA#		MA000932210						
Package		PG-MQFP-144-8		Weight*		4198.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	36.251	0.86	0.86	8634	8634
leadframe	non noble metal	magnesium	7439-95-4	0.976	0.02		232	
	inorganic material	silicon	7440-21-3	4.227	0.10		1007	
	non noble metal	nickel	7440-02-0	19.510	0.46		4647	
	non noble metal	copper	7440-50-8	625.625	14.90	15.48	149013	154899
wire	noble metal	gold	7440-57-5	5.612	0.13	0.13	1337	1337
encapsulation	organic material	carbon black	1333-86-4	10.410	0.25		2480	
	plastics	epoxy resin	-	440.706	10.50		104968	
	inorganic material	silicondioxide	60676-86-0	3019.012	71.93	82.68	719075	826523
leadfinish	non noble metal	tin	7440-31-5	19.066	0.45	0.45	4541	4541
plating	noble metal	silver	7440-22-4	10.582	0.25	0.25	2521	2521
glue	plastics	acrylic resin	-	1.297	0.03		309	
	noble metal	silver	7440-22-4	5.190	0.12	0.15	1236	1545
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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